

## Supporting Information

### **Fabrication and Size Dependent Properties of Porous Silicon Nanotube Arrays**

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### **Experimental Details**

**ZnO NWA fabrication.** ZnO NWA templates were prepared on FTO glass (1.5 cm x 1.5 cm, TEC-15, MTI Co.) seeded preliminarily in a mixture solution (1:1 v:v) 0.03 M Zn(NO<sub>3</sub>)<sub>2</sub> and 0.03 M hexamethylenetetramine at 92 °C for 10-40 h. Polyethylenimine (100 µl, branched, low molecular weight, Aldrich) was added into 100 ml of ZnO growth solution to adjust the ratio of L/D of ZnO NWs when desired. A ZnO seed layer was formed by spin-coating a mixture of 0.01 M zinc acetate (in methanol) and 0.03M NaOH (also in methanol) (4:1 V:V) onto FTO substrates (without heating and stirring), followed by an oxidative treatment in air at 250 °C for 20 min.

**Si NTA Fabrication.** A ZnO NWA sample was inserted into a quartz tube reactor and Si deposition on the ZnO NWA was achieved through the use of silane (15 sccm, 0.5% in He) mixed with He carrier gas (150 sccm) that was passed through a furnace operating at 500 °C for 8 min. These Si-coated ZnO NW samples were then placed in another quartz reactor and heated to 450°C; NH<sub>4</sub>Cl was loaded in an alumina boat located upstream and heated to 350°C. The gaseous etchant was transported via He gas downstream (100 sccm) to the furnace for 1 hr for removal of the ZnO NWA substrate.

**Confocal Microscopy/Spectroscopy.** Fluorescence lifetime microscopy and associated imaging measurements were conducted on a Microtime 200 system from PicoQuant, GmbH (Berlin, Germany). Excitation was provided by a 470 nm pulsed laser diode operating at 20 MHz, which was directed into the sample by a 60x 1.2 NA water immersion objective, part of an Olympus IX71 microscope. Scattered light was removed by a 473 and 500 long pass filters, and the light passed through a 30  $\mu\text{m}$  pinhole. The signal was detected by a single photon avalanche diode from Perkin Elmer (SPCM-AQR-14). All data processing was performed by SymPhoTime software, version 5.3.2, also from PicoQuant.

### Supporting Figures

**Supporting Figure 1.** Cross sectional SEM image of a ZnO NWA film achieving 14  $\mu\text{m}$  in length with an average diameter of  $\sim 120$  nm.

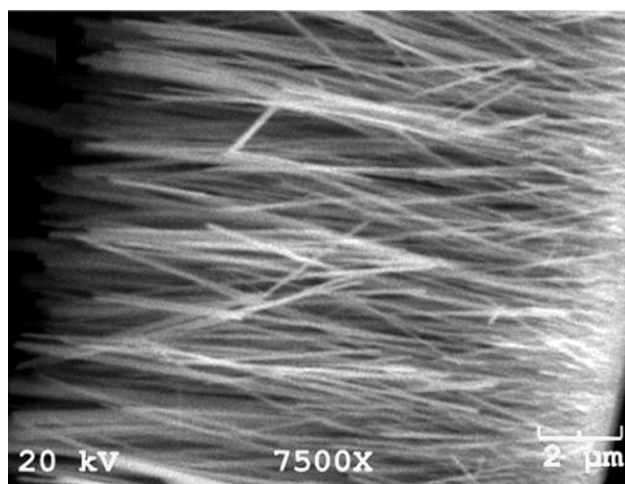
**Supporting Figure 2.** (a) TEM image of Si NT (top) and Si/ZnO NW (bottom); EDX linescans of (b) Si NT (produced by etching of ZnO core) and (c) Si/ZnO NW.

**Supporting Figure 3.** TEM image of Si NT sample with relatively thick sidewalls of 70 nm on 100 nm ID hollow structure; scale bar = 50 nm.

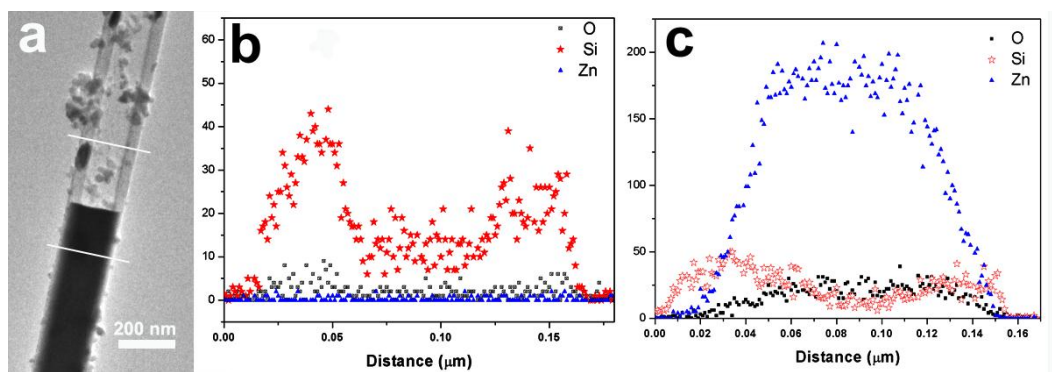
**Supporting Figure 4.** (a) TEM image of densely-packed Si NTA film; NT lengths reach values of 3  $\mu\text{m}$  in such films (scale = 200 nm); (b) HREM image of an annealed Si NT.

**Supporting Figure 5.** (c) Porous Si NTs (after annealing at 600  $^{\circ}\text{C}$  for 30 min). Inset: HRTEM lattice image of Si NTs. (d) Amorphous Si NTs with large thickness (after annealing at 600  $^{\circ}\text{C}$  for 30 min). Scale bars are 200 nm and 20 nm for (a) and (b), respectively.

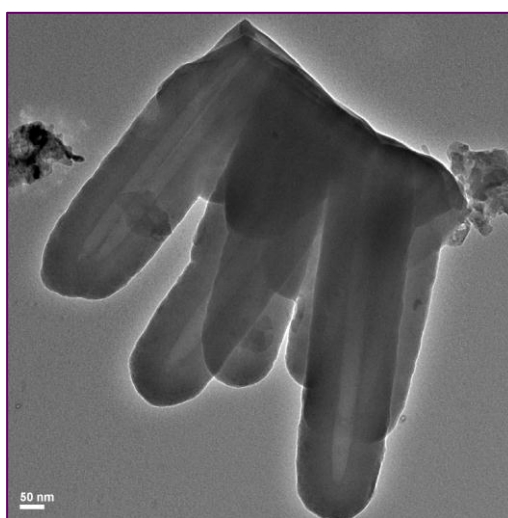
**Supporting Figure 6.** Dissolution of Si NTs possessing a 10 nm thick shell in phosphate-buffered saline at 37 $^{\circ}\text{C}$  as a function of time (in hours).



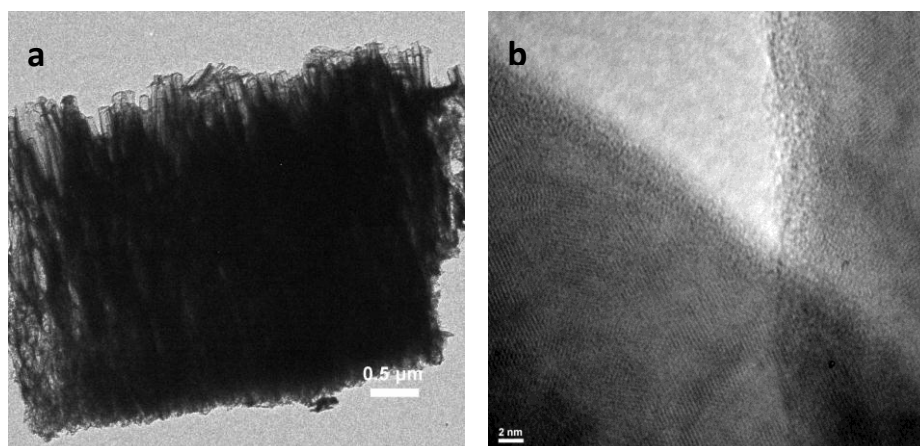
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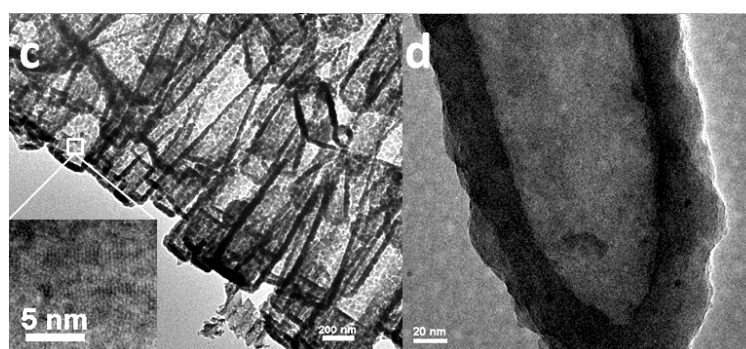
**Supporting Figure 2.** (a) TEM image of Si NT (top) and Si/ZnO NW (bottom); EDX line scans of (b) Si NT (produced by etching of ZnO core) and (c) Si/ZnO NW.



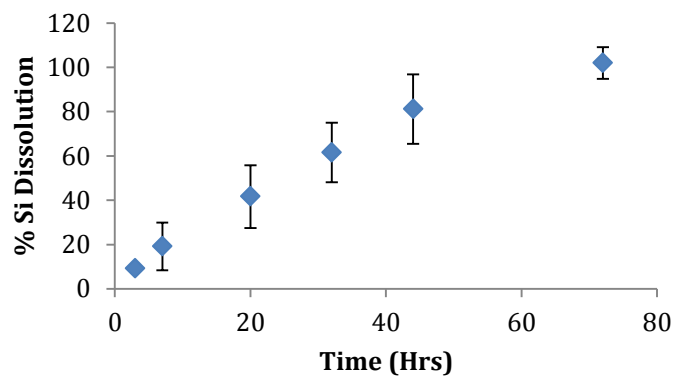
**Supporting Figure 3.** TEM image of Si NT sample with relatively thick sidewalls of 70 nm on 100 nm ID hollow structure; scale bar = 50 nm.



**Supporting Figure 4.** (a) TEM image of densely-packed Si NTA film; NT lengths reach values of 3  $\mu\text{m}$  in such films (scale = 200 nm); (b) HREM image of an annealed Si NT showing lattice spacings associated with the  $\langle 111 \rangle$  orientation (inset: corresponding FFT image); scale bar = 2 nm



**Supporting Figure 5.** (c) Porous Si NTs (after annealing at 600  $^{\circ}\text{C}$  for 30 min). Inset: HRTEM lattice image of Si NTs. (d) Amorphous Si NTs with large thickness (after annealing at 600  $^{\circ}\text{C}$  for 30 min). Scale bars are 200 nm and 20 nm for (a) and (b), respectively.



**Supporting Figure 6.** Dissolution of Si NTs possessing a 10 nm thick shell in phosphate-buffered saline at 37 $^{\circ}\text{C}$  as a function of time (in hours).